



Specifications Datasheet

Module supports:



Module Part Number:

| Module # | Module Name | HT Part Number | remark |
|----------|---------------------|----------------|--------|
| #1 | NXP5169LIGHT MODULE | HTMD-004B | |

| Role | Name: | Appointment: | Signature: |
|----------------|----------------|-----------------|------------|
| Author | Li Dan | Design Engineer | |
| Checked by | Nick Qiao | PM – R&D | |
| Approved by | Yin Zhi Lin | CTO | |
| Date: | Classification | Version: | Status: |
| <31 July 2018> | Confidential | <V0.1> | <Draft> |



Revision History:

| Version | Date (dd/mm/yyyy) | Author | Status | Modifications |
|---------|----------------------|--------|--------|-----------------|
| V0.1 | 31/07/2018 | Li Dan | Draft | Doc creation |
| V0.2 | 22/08/2018 | Li Dan | Draft | Add 5169 module |
| V0.3 | 7/9/2018 | Li Dan | Draft | Add parameter |
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1 Introduction

1.1 Scope

| Module # | Module Name | HT P/N | SOC | Standard Supported | RF Frequency Band | Interface to Host | Module Size |
|----------|---------------------|-----------|--------|--------------------|------------------------|-------------------|-----------------------------|
| #1 | NXP5169LIGHT MODULE | HTMD-004B | JN5169 | Zigbee 3.0 | ♦ 2.4G (2.4 ~ 2.5 GHz) | UART | 22mm x 15mm(W) x 3mm(H) (L) |



1.2 Product Features

- 1) Embedded 32-bit high performance MCU with clock up to 48MHz.
- 2) Program memory: internal 512KB Flash.
- 3) Data memory: 32KB on-chip SRAM.
- 4) 32MHz Crystal
- 5) A rich set of I/Os:
 - ✧ Up to 36/21 GPIOs depending on package option;
 - ✧ DMIC (Digital Mic);
 - ✧ AMIC (Analog Mic);
 - ✧ Mono-channel Audio output;
 - ✧ SPI;
 - ✧ I2C;
 - ✧ UART with hardware flow control;
 - ✧ USB;
 - ✧ Debug Interface.
- 6) Up to 6 channels of PWM, 2-channel IR.
- 7) Sensor:
 - ✧ 14bit ADC with PGA;
 - ✧ Temperature sensor.



- 8) One quadrature decoder.
- 9) Embedded hardware AES.
- 10) Operating temperature:
 - ✧ ET versions: -40°C~+85°C temperature range;
 - ✧ AT versions: -40°C~+125°C temperature range.

RF features include:

- 1) Rx Sensitivity: -97dBm@ IEEE802.15.4 250Kbps,
- 2) TX output power:11dBm
- 3) Single-pin antenna interface
- 4) RSSI monitoring.

Features of power management module include:

- 1) Embedded LDO.
- 2) Battery monitor: Supports low battery detection.
- 3) Power supply: 1.9V~3.6V.
- 4) Multiple stage power management to minimize power consumption.
- 5) Low power consumption:



- ✧ Receiver mode current: 12mA
- ✧ Transmitter mode current: 15mA @0dBm power, 22mA @max power
- ✧ Suspend mode current: 10uA (IO wakeup), 12uA (Timer wakeup)
- ✧ Deep sleep mode current: 1.7uA

Zigbee RF4CE features include:

- 1) Based on IEEE 802.15.4 Standard, certified RF4CE platform, with ZRC1.1/ZRC2.0 and MSO profile support;
 - 2) Various transmission options including broadcast;
 - 3) Provides a secured key generation mechanism;
 - 4) Supports a simple pairing mechanism for devices with full application confirmation;
 - 5) Only authorized devices are able to communicate;
-
- 6) Various power saving modes are supported for all device classes;
 - 7) Supports AES-128bit encryption;
 - 8) Extensible to vendor specific profiles;
 - 9) Telink extended profile with audio support for voice command based searches;
 - 10) Over the air (OTA) firmware upgrade with hardware support.



Ambient Conditions:

- Operation Temperature: -10°C ~ +120°C
- Storage Temperature: -40°C ~ +85°C
- Operation Humidity: 10 ~ 90% RH
- Storage Humidity: 5 ~ 95% RH

Environmental compliance:

- RoHS compliant
- REACH compliant



2 Technical Specifications

2.1 Absolute Maximum Ratings:

Stresses beyond these conditions listed below may cause permanent damage to the module.

| Parameters | Maximum Rating |
|--------------------------------|-----------------|
| Power Supply Voltage at +3V3 | (-0.3 ~3.63)V |
| Input voltage to IO pins | (-0.3 ~3.63)V |
| Storage Temperature Conditions | -40 °C ~ +85°C. |
| Storage Humidity conditions | 5% to 95% (RH) |
| ESD (HBM) | 1000V |

2.2 Recommended Operation Conditions

| Parameters | Operation Conditions |
|-------------------------------|---|
| Operating Temperature | (-10 °C ~ +120°C) |
| Conditions | - No performance reduction up 80°C ambient Temperature |
| | - No component failure up to 120°C ambient Temperature. |
| Operating Humidity conditions | 10% to 90% (RH) |
| | |



2.3 Electrical Specifications

Pre-test conditions:

- 1 Operation Temperature = room temperature 25°C, unless otherwise noted.
- 2 CTQ parameters are marked with *.

| Item No. | Parameters | Test Conditions | Specifications/Requirement | | | |
|----------|-------------|---|--|------|------|-------|
| | | | Min | Typ | Max | Units |
| 2.3.1 | Input power | Test board | 2.8V | 3.3V | 3.6V | V |
| 2.3.2 | Power | standby | | | | mA |
| 2.3.3 | consumption | Active | | | | mA |
| 2.3.4 | ESD | EN61000-3-2/3-3: ESD - IEC61000/4/2 : 8kV air - ANATEL 442 : 8kV air discharge Module is mounted into Final product casing at the designed location. | No functional failures and no parts should suffer damage | | | |

2.4 RF Performance

- 1) TX power is at typical level, measured at antenna feed point.
- 2) Front End Insertion loss (including Balun, impedance mis-match+diplexer)
- 3) Operation Temperature = room temperature 25°C, unless otherwise noted.
- 4) CTQ parameters are marked with *.

2.4.1 Zigbee RF Specifications

| Item No. | Parameters | Test Conditions | Specifications/Requirement | | | |
|----------|----------------------|---|----------------------------|-----|-----|-------|
| | | | Min | Typ | Max | Units |
| 2.4.2.1 | receiver sensitivity | 2405 nominal for 1 % PER, as per 802.15.4 | | -97 | | dBm |



| | | | | | | |
|---------|-------|---|--|-------|--|-----|
| 2.4.2.2 | Power | 2440 nominal for 1 % PER, as per 802.15.4 | | -97 | | dBm |
| 2.4.2.3 | | 2480 nominal for 1 % PER, as per 802.15.4 | | -97 | | dBm |
| 2.4.2.4 | | 2405 | | 10.70 | | dBm |
| 2.4.2.5 | | 2440 | | 10.03 | | dBm |
| 2.4.2.6 | | 2480 | | -7.62 | | dBm |
| | | | | | | |

2.5 Quality, Environmental and Reliability

| S/N | Electrical Test Requirement | TEST CONDITION | Requirement |
|-------|------------------------------|---|-------------|
| 2.5.1 | Dry heat Test | Temp. : +70°C Test time : 96 hrs | 4 days |
| 2.5.2 | Low Temperature storage | Temp. : -25°C Test time : 96 hrs | 4 days |
| 2.5.3 | Temperature Shock | Temp. : -20°C ~ +85°C, Duration : 30 min Ramp-up & Ramp-down for 5 min, Cycle : 1,000cycle. | 35 days |
| 2.5.4 | Humidity Load Test | Leave samples in 40°C±5°C, 90 ~ 95% RH for 21days, and in standard test condition for 30 minutes | 21 days |
| 2.5.5 | Vibration test | 10-55-10Hz / amplitude 0.35mm / sweep rate 1 octave per min. | 1 day |
| 2.5.6 | Cold Test | Operational/start up after min 4hrs at -10°C | 1 day |
| 2.5.7 | Damp heat cyclic | Humidity 93%RH, 6h:temp from 25 °C to 40 °C, 6hrs temp 40 °C to 25 °C, 6hrs at 25 °C, operational last hour only for 21 days. | 21 days |
| 2.5.8 | Temperature step stress test | Operational up to a temperature of 60 °C for 16 days | 16 days |



| | | | |
|-------|-------------------------|---------------------------------------|---------|
| 2.5.9 | Operation Life(MTBF) | Temp. : 60°C, 90% RH, MTBF 50,000 hrs | 10 days |
|-------|-------------------------|---------------------------------------|---------|

2.6 EMC Compliance and Certifications

| Region | Regulation Standards | Requirement |
|--------|----------------------|---|
| EU/RU | | Fulfill CE with official test report at module level to meet the latest EMC requirement |
| LATAM: | | Fulfill approbation requirements, with official test report at Module level |
| | | |

2.7 Environment Compliance

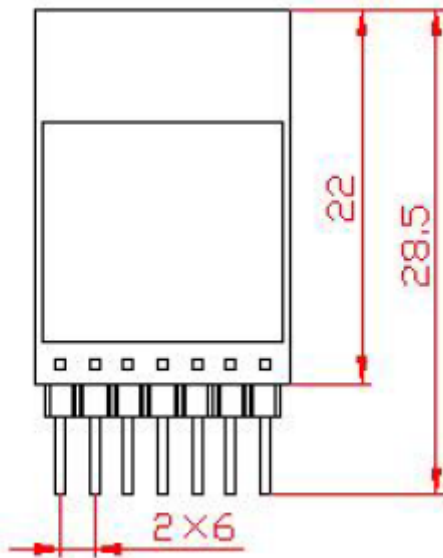
- RoHS compliant
- REACH compliant



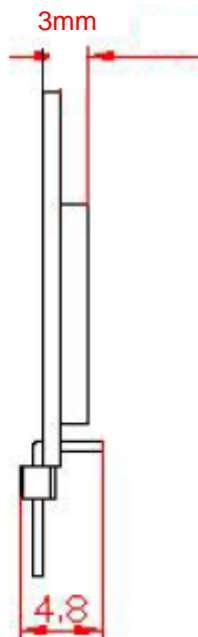
3 Mechanical Drawing

3.1 Mechanical Outline and dimensions

Dimension (TOP View)

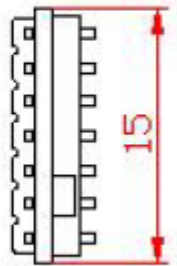


Dimension (Side View)





Dimension (Bottom View)



3.2 Actual Module image





FCC Statement:

Any Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) This device must accept any interference received, including interference that may cause undesired operation.

FCC Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment .

This equipment should be installed and operated with minimum distance 20cm between the radiator& your body.

FCC Label Instructions:

The outside of final products that contains this module device must display a label referring to the enclosed module. This exterior label can use wording such as: "Contains Transmitter Module FCC ID: PUW-HTMD004B or Contains FCC ID: PUW-HTMD004B " , Any similar wording that expresses the same meaning may be used.